



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

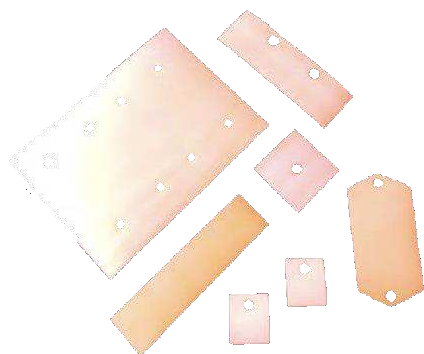
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



## 60°C/140°F PHASE-CHANGE TEMPERATURE



## FEATURES AND BENEFITS

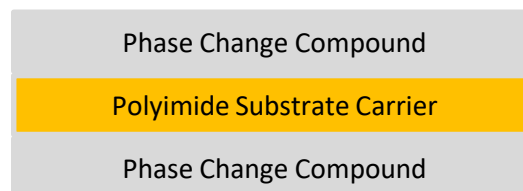
- Low Thermal Impedance
- Excellent Replacement for Thermal Greases
- Thixotropic / Prevents Compound Run-Out
- Excellent Mechanical & Dielectric Properties
- Cost Effective “Drop in Place” Solution
- RoHS and Halogen Free Compliant



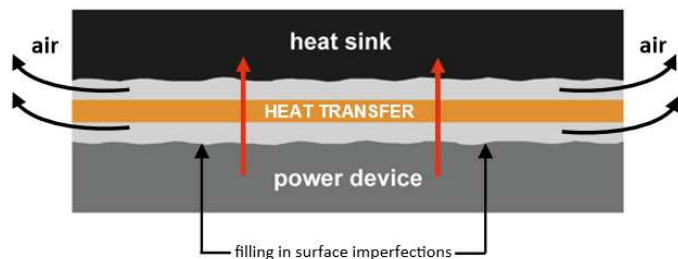
Wakefield-Vette's *ulTIMiFlux* line of thermal interface materials offer high performance, low cost, configurability and custom sizes for your thermal system needs. Thermal Interface Materials (TIM) are a secondary material installed between the heat sink and the device which are designed to improve the thermal transfer to the heat sink. Regardless of how flat or smooth the device and heat sink are, there will always be small air voids between the two surfaces. Since air is not a great conductor of heat, a TIM replaces the air and fills the voids. There are many types of TIMs and each has its best case usages. Wakefield-Vette's line of dielectric phase change thermal materials are intended to fill voids between a device and the heat sink and utilize a polyimide film to act as a thermally conductive carrier in order to deliver a uniform thickness coating of phase-change thermal compound on both sides.

Through the development of this unique formulation, Wakefield-Vette's phase change solution offers efficient thermal transfer by phase-changing during normal device operating temperatures while maintaining a uniform bond line thus driving out the air and adjusting for any surface imperfections or flatness conditions that may exist across the interface. This construction is useful in a wide range of electronic cooling applications from transistors, diodes or any type of heat generating non-isolated power device.

## Standard Phase Change Pad Construction



A primary advantage of utilizing a phase-change system is the ability to drive out air from within the interface during initial device cycling causing phase change and surface wetting of the thermal compound coating. The phase-change compound is available in specific die cut patterns for common TO packages and can be placed instantly and immediately ready for component mounting. Due to its thixotropic formulation design, compound is held within the interface with no worries of run-out into unwanted areas during normal device/component operation.



Note: during initial phase-change, it is recommended to re-check your torque settings if device utilizes a screw mounting system. Applying additional torque during initial phase change will thin the material bond line slightly leading to improved thermal performance.

## CD-02-05

Wakefield-Vette's phase-change product is a solvent free high performance dielectric thermal interface material that is designed to provide efficient thermal transfer by providing precision phase-change and a uniform bond line thickness across a device/component mounting interface. The pads are designed as a pre-formed thermally conductive “drop in place” solution that offers excellent thermal transfer characteristics. From an installation perspective, thermal greases are difficult to dispense as well as provide inadequate coverage and a uniform thickness across the interface most often leaving trapped air leading to poor thermal transfer. Not to mention the thermal grease clean up required in unwanted areas afterwards.

Wakefield-Vette offers the following pad sizes and die-cut TO package sizes for ease of installation:

| WV Part Number     | Description  | Size                                | For use with                 |
|--------------------|--|-------------------------------------|------------------------------|
| CD-02-05-220       | Phase Change TO-220 Pad with mounting hole                   | 0.70" x 0.50", single mounting hole | TO-220, with mounting holes  |
| CD-02-05-247       | Phase Change TO-247 Pad with mounting hole                   | 0.95" x 0.75", single mounting hole | TO-247, with mounting holes  |
| CD-02-05-264       | Phase Change TO-264 Pad with mounting hole                   | 1.05" x 0.85", single mounting hole | TO-264, with mounting holes  |
| CD-02-05-025       | Phase Change 1" x 1" Square Pad                              | 1" x 1", no holes                   | General Use                  |
| CD-02-05-127       | Phase Change 5" x 5" Square Pad                              | 5" x 5", no holes                   | General Use                  |
| CD-02-05-190       | Phase Change 7.75" x 10.00" Rectangular Pad                  | 7.75" x 10.00", no holes            | General Use                  |
| CD-02-05-LED-1     | Phase Change LED 1 Inch OD Circle Pad                        | 1.00" Diameter Circle, No ID        | LED                          |
| CD-02-05-LED-2     | Phase Change LED 2 Inch OD Circle Pad                        | 2.00" Diameter Circle, No ID        | LED                          |
| CD-02-05-220-N     | Phase Change TO-220 Pad, NO HOLE                             | 0.70" x 0.50" NO HOLE               | TO-220 with no mounting hole |
| CD-02-05-247-N     | Phase Change TO-247 Pad, NO HOLE                             | 0.95" x 0.75" NO HOLE               | TO-247 with no mounting hole |
| CD-02-05-220-2     | Phase Change Dual Mount TO-220 Pad, 2 holes                  | 1.00" x 0.50" 2 holes               | Dual Mount TO-220            |
| CD-02-05-220-3     | Phase Change Triple Mount TO-220 Pad, 3 holes                | 1.50" x 0.50", 3 holes              | Triple Mount TO-220          |
| CD-02-05-247-2     | Phase Change Dual Mount TO-247 Pad, 2 holes                  | 1.50" x 0.95", 2 holes              | Dual Mount TO-247            |
| CD-02-05-247-3     | Phase Change Triple Mount TO-247 Pad, 3 holes                | 2.25" x 0.95", 3 holes              | Triple Mount TO-247          |
| CD-02-05-218       | Phase Change TO-218 Pad with hole                            | 0.80" x 0.60" with hole             | TO-218 with mounting hole    |
| CD-02-05-126       | Phase Change TO-126 Pad with hole                            | 0.50" x 0.35" with hole             | TO-126 with mounting hole    |
| CD-02-05-66        | Phase Change TO-66 Pad, 2 pin                                | 1.25" x 0.70", 2 pin                | TO-66 (std 2 pin)            |
| CD-02-05-3-2       | Phase Change TO-3 Pad, 2 pin                                 | 1.55" x 1.05", 2 pin                | TO-3 (2 pin configuration)   |
| CD-02-05-3-4       | Phase Change TO-3 Pad, 4 pin                                 | 1.55" x 1.05", 4 Pin                | TO-3 (4 pin configuration)   |
| CD-02-05-3-8       | Phase Change TO-3 Pad, 8 pin                                 | 1.55" x 1.05", 8 Pin                | TO-3 (8 pin configuration)   |
| CD-02-05-DO4       | Phase Change DO-4 Pad, 0.625" OD / 0.203" ID                 | 0.625" OD / 0.203" ID               | DO-4                         |
| CD-02-05-DO4-5     | Phase Change DO4/5 Pad 0.800" OD / 0.260" ID                 | 0.800" OD / 0.260" ID               | DO-4 / DO-5                  |
| CD-02-05-DO5       | Phase Change DO-5 Pad 1.00" OD / 0.250" ID                   | 1.00" OD / 0.250" ID                | DO-5                         |
| CD-02-05-REC-125   | Phase Change Rectifier Pad 1.25" x 1.25" with hole           | 1.25" x 1.25" with hole             | Rectifier                    |
| CD-02-05-REC-125-N | Phase Change Rectifier Pad 1.25" X 1.25", NO HOLE            | 1.25" X 1.25", NO HOLE              | Rectifier                    |
| CD-02-05-REC-112   | Phase Change Rectifier Pad 1.12" x 1.12" with hole           | 1.12" x 1.12" with hole             | Rectifier                    |
| CD-02-05-BRI-225   | Phase Change Bridge Rectifier Pad 2.25" x 1.75", 2 End Slots | 2.25" x 1.75", 2 End Slots          | Bridge Rectifier             |
| CD-02-05-C-18      | Phase Change Chipset Pad 0.689" x 0.689", No Hole            | 0.689" x 0.689", No Hole            | 17.5mm x 17.5mm, chipset     |
| CD-02-05-C-20      | Phase Change Chipset Pad 0.768" x 0.768", No Hole            | 0.768" x 0.768", No Hole            | 19.5mm x 19.5mm, chipset     |
| CD-02-05-C-22      | Phase Change Chipset Pad 0.846" x 0.846", No Hole            | 0.846" x 0.846", No Hole            | 21.5mm x 21.5mm, chipset     |
| CD-02-05-C-26      | Phase Change Chipset Pad 1.003" x 1.003", No Hole            | 1.003" x 1.003", No Hole            | 25.5mm x 25.5mm, chipset     |
| CD-02-05-C-34      | Phase Change Chipset Pad 1.319" x 1.319", No Hole            | 1.319" x 1.319", No Hole            | 33.5mm x 33.5mm, chipset     |
| CD-02-05-C-39      | Phase Change Chipset Pad 1.516" x 1.516", No Hole            | 1.516" x 1.516", No Hole            | 38.5mm X 38.5mm, chipset     |
| CD-02-05-C-46      | Phase Change Chipset Pad 1.811" x 1.811", No Hole            | 1.811" x 1.811", No Hole            | 46mm X 46mm, chipset         |
| CD-02-05-C-49      | Phase Change Chipset Pad 1.909" x 1.909", No Hole            | 1.909" x 1.909", No Hole            | 48.5mm X 48.5mm, chipset     |
| CD-02-05-C-54      | Phase Change Chipset Pad 2.106" x 2.106", No Hole            | 2.106" x 2.106", No Hole            | 53.5mm x 53.5mm, chipset     |

Specific tests should be performed by the end user to determine the product suitability for the particular application. Contact Wakefield-Vette sales and engineering support with any inquiries.

## CD-02-05

Wakefield-Vette's phase-change product physical properties / characteristics:

| Property/Characteristics                        | Value  |
|---|--|
| Base Phase Change Formulation                   | Proprietary  |
| Electrical Isolation                            | 9200V  |
| Phase Change Temperature                        | 60oC / 140oF   |
| Viscosity @ Phase Change                        | Thixotropic  |
| Overall Thickness                               | 0.003” +/- 10%   |
| Color   | Orange   |
| Separator Liner / Color                         | White  |
| Total Mass Loss, % TML                          | 0.138  |
| Collectible Volatile, Condensable Matter, % CVC | 0.130  |
| Water Vapor Gain, % WVR                         | 0.021  |
| Storage Condition and Temperature               | Cool Dry Location at or below 35oC / 95oF  |
| Shelf Life                                      | Indefinite if stored per conditions above  |
| Transit Methods / Conditions                    | Due to temperature sensitive design, it is recommended to ship air freight during warmer months to prevent phase-change of thermal compound during long ground transit (May-September) |
| Thermal Impedence                               | 0.107 oC-in <sup>2</sup> / Watt (@100 PSI)   |
| UL Flammability Rating                          | UL94V-0  |

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